



The 25<sup>th</sup> IEEE Intersociety Conference  
on Thermal and Thermomechanical  
Phenomena in Electronic Systems

JW Marriott Orlando - Grande Lakes,  
Orlando, FL, May 26 – 29, 2026

## Keynotes

Application/Nomination Link: [Click Here](#)

Deadline: **March 30, 2026**

ITherm has three keynote session, on the mornings of May 27, 28 and 29<sup>th</sup>. Keynotes are 60-minute plenary sessions on a key topic for the field and is given by a recognized leader in the area.

ITherm is seeking keynotes in the following areas of interest. Thought provoking and exploratory talks outside of these suggested areas are also welcome and can be described in the application form.

- Advanced and 3D Packaging
- Computing in Aerospace/Extreme Environments
- Quantum Computing
- Hyperscale Computing and Data Centers
- Standardization and Regulation
- Agentic AI for Thermal Design
- Modular Power and Cooling Infrastructure to Support AI
- Siting of Data Centers – Engineering and Policy

Keynote speakers are provided free registration to the conference and one night at the conference hotel.

If you are interested in this opportunity, please use the link above to apply for a keynote speaking slot. You can also use this form to nominate someone you know for one of these events, and the organizers will reach out to the nominee to confirm their participation and details of the talk.

ITherm 2025 featured the following keynote speakers. A full listing of prior keynotes can be found on the conference website ([click here](#)):

- **Raja Swaminathan**, Corporate VP of AMD
- **Scott Parent**, VP and Field CTO, Energy / Aerospace / Industrials, Ansys
- **Cullen Bash**, VP of R&D, HP Labs

For further information please contact

Keynotes Chair: **Prof. J. Weibel** <[jaweibel@purdue.edu](mailto:jaweibel@purdue.edu)>

General Chair: **Dr. M. P. David** <[milnespd@us.ibm.com](mailto:milnespd@us.ibm.com)>

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